



Material Content Data Sheet



Sales Product Name		BTM7710G		Issued		20. July 2018		
MA#		MA001364464						
Package		PG-DSO-28-22		Weight*		810.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.882	1.59	1.59	15886	15886
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7096	
wire	non noble metal	copper	7440-50-8	233.637	28.81	29.57	288126	295666
	non noble metal	aluminium	7429-90-5	1.583	0.20	0.20	1952	1952
	encapsulation	organic material	carbon black	1333-86-4	1.095	0.14		1350
encapsulation	plastics	epoxy resin	-	78.300	9.66		96561	
	inorganic material	silicondioxide	60676-86-0	468.155	57.73	67.53	577339	675250
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6135	6135
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	836	836
glue	plastics	epoxy resin	-	0.607	0.07		748	
	noble metal	silver	7440-22-4	2.860	0.35	0.42	3527	4275
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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